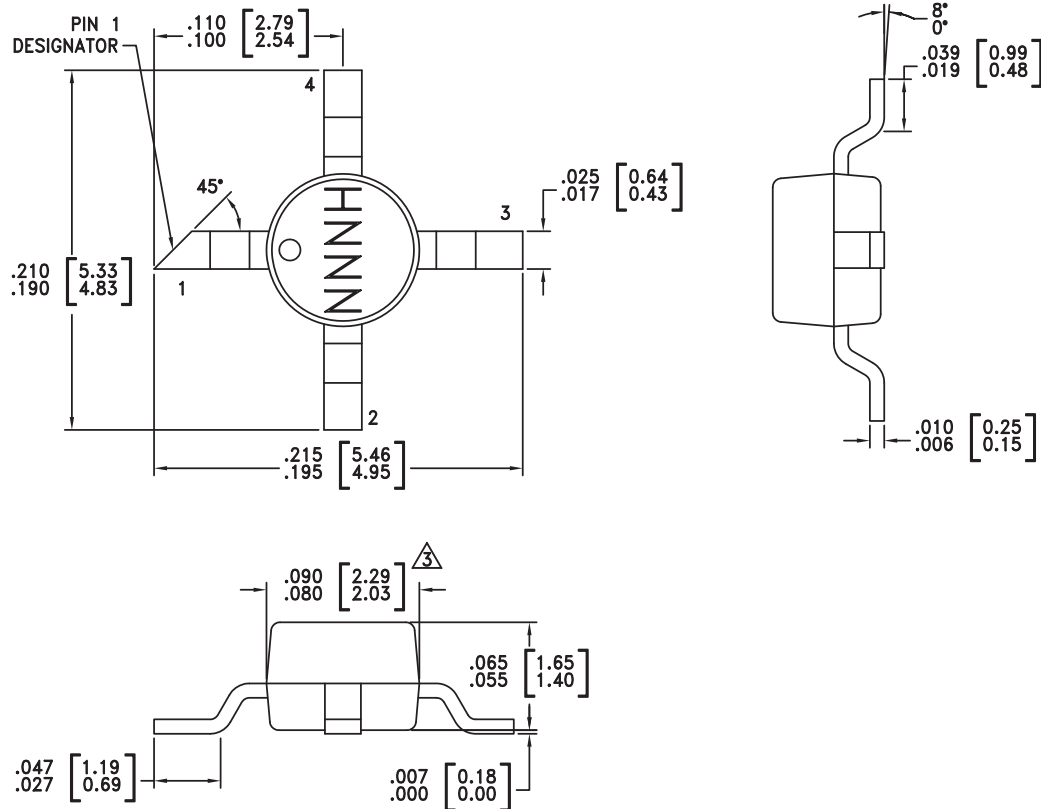


MP86 (E) – 4 LEAD PLASTIC MICRO-P PLASTIC PACKAGE (A.K.A. MICRO-X)

MP86 (E) Package Outline Drawing



NOTES:

- LEADFRAME MATERIAL: COPPER ALLOY
- DIMENSIONS ARE IN INCHES [MILLIMETERS]
- Δ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- THE MICRO-P PACKAGE IS DIMENSIONALLY COMPATIBLE WITH THE "MICRO-X PACKAGE"

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
MP86	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 ^[1]	HNNN
MP86E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 ^[2]	<u>HNNN</u>

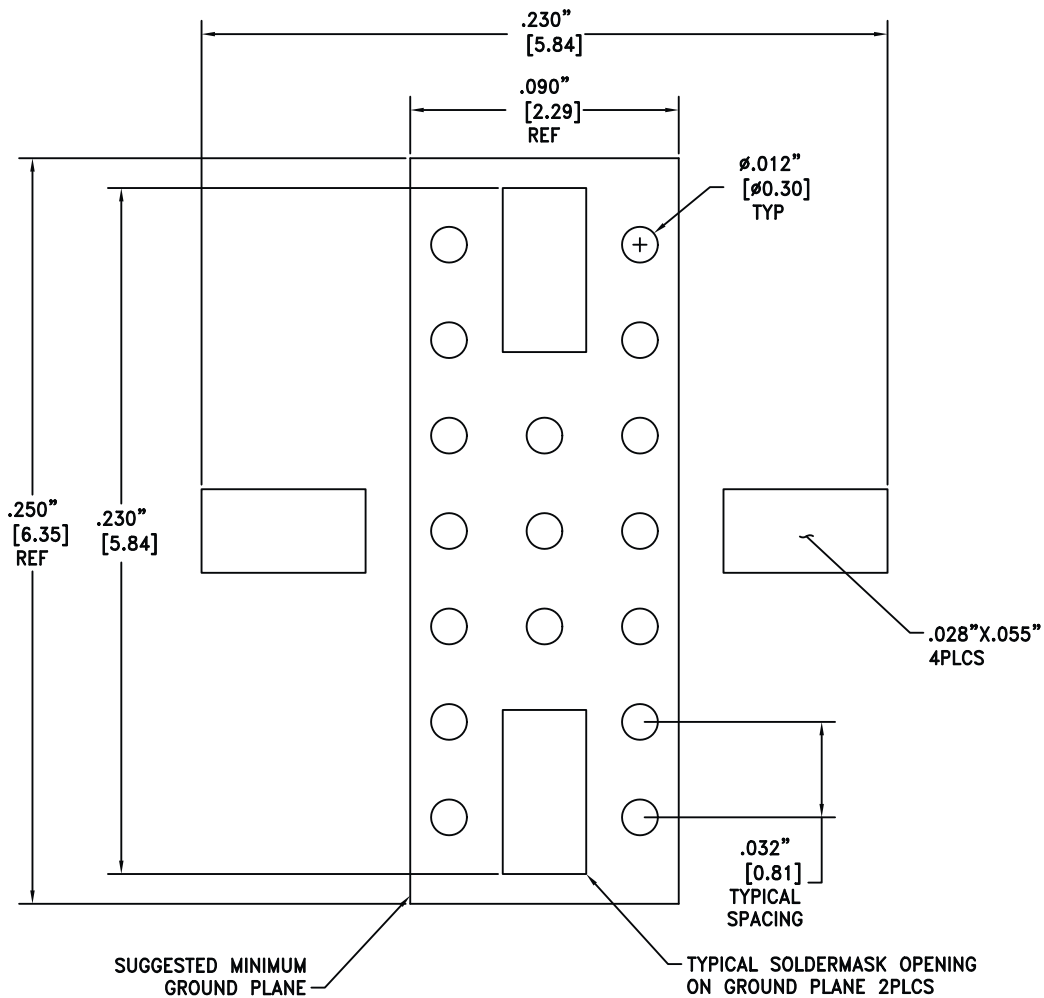
[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 3-Digit part number NNN

MP86 (E) – 4 LEAD PLASTIC MICRO-P PLASTIC PACKAGE (A.K.A. MICRO-X)

Suggested MP86 (E) PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.